

# The Intel® Xeon® Processor E5 Family

## Architecture, Power Efficiency, and Performance

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August 2012

### Agenda

1. Architecting Performance
2. Energy Efficiency from the Load Line to the Data Center
3. Measured Performance

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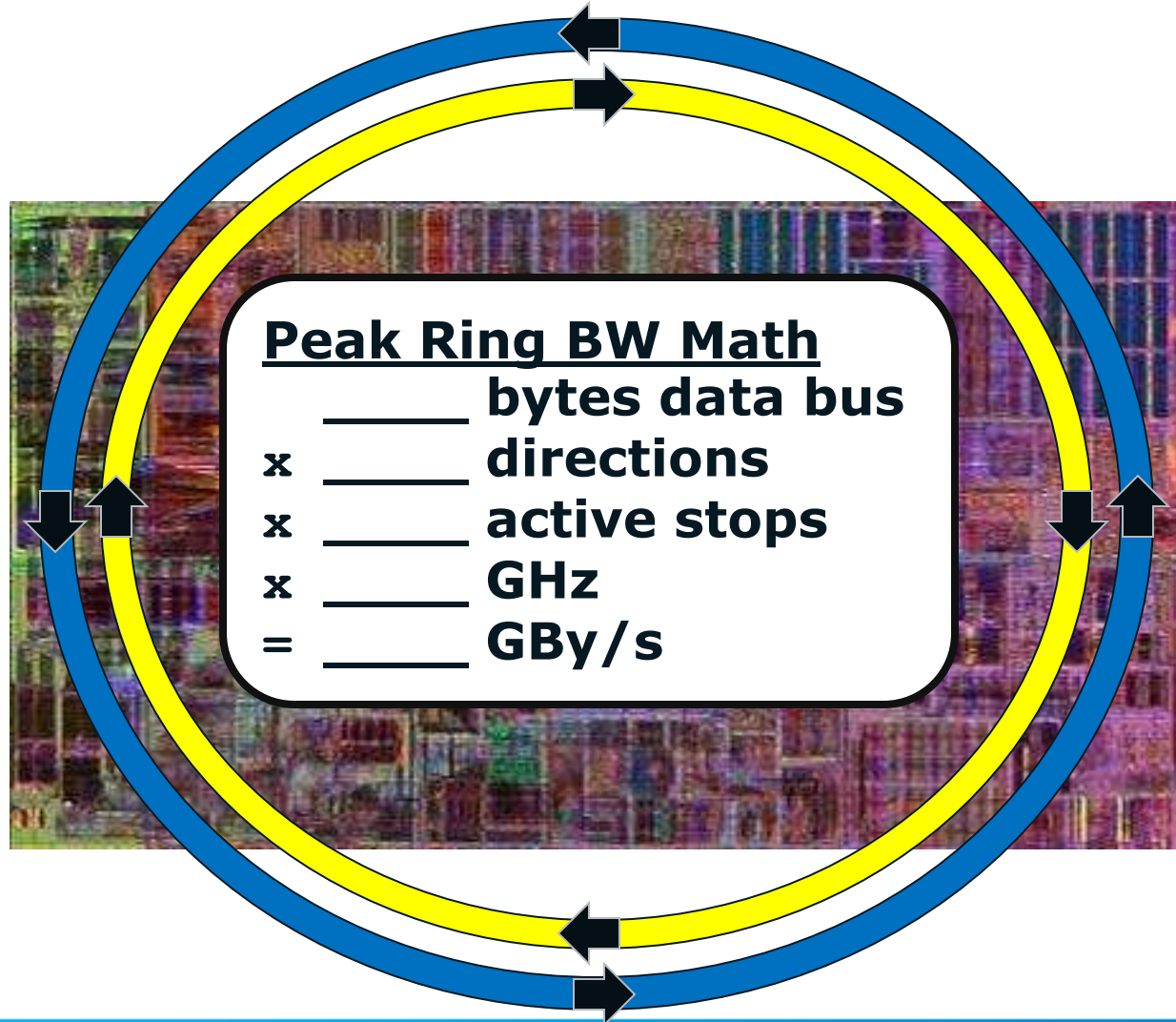
## Foundations of SNB-EP Performance

### Start with the Sandy Bridge Core

<b>Execution Units</b>	<b>L1 Data Cache</b>	<b>L2 Cache &amp; Interrupt Servicing</b>
	<b>Memory Ordering &amp; Execution</b>	<b>Paging</b>
<b>Out-of-Order Scheduling &amp; Retirement</b>	<b>Instruction Decode &amp; Microcode</b>	<b>Branch Prediction</b>
		<b>Instruction Fetch &amp; L1 Cache</b>

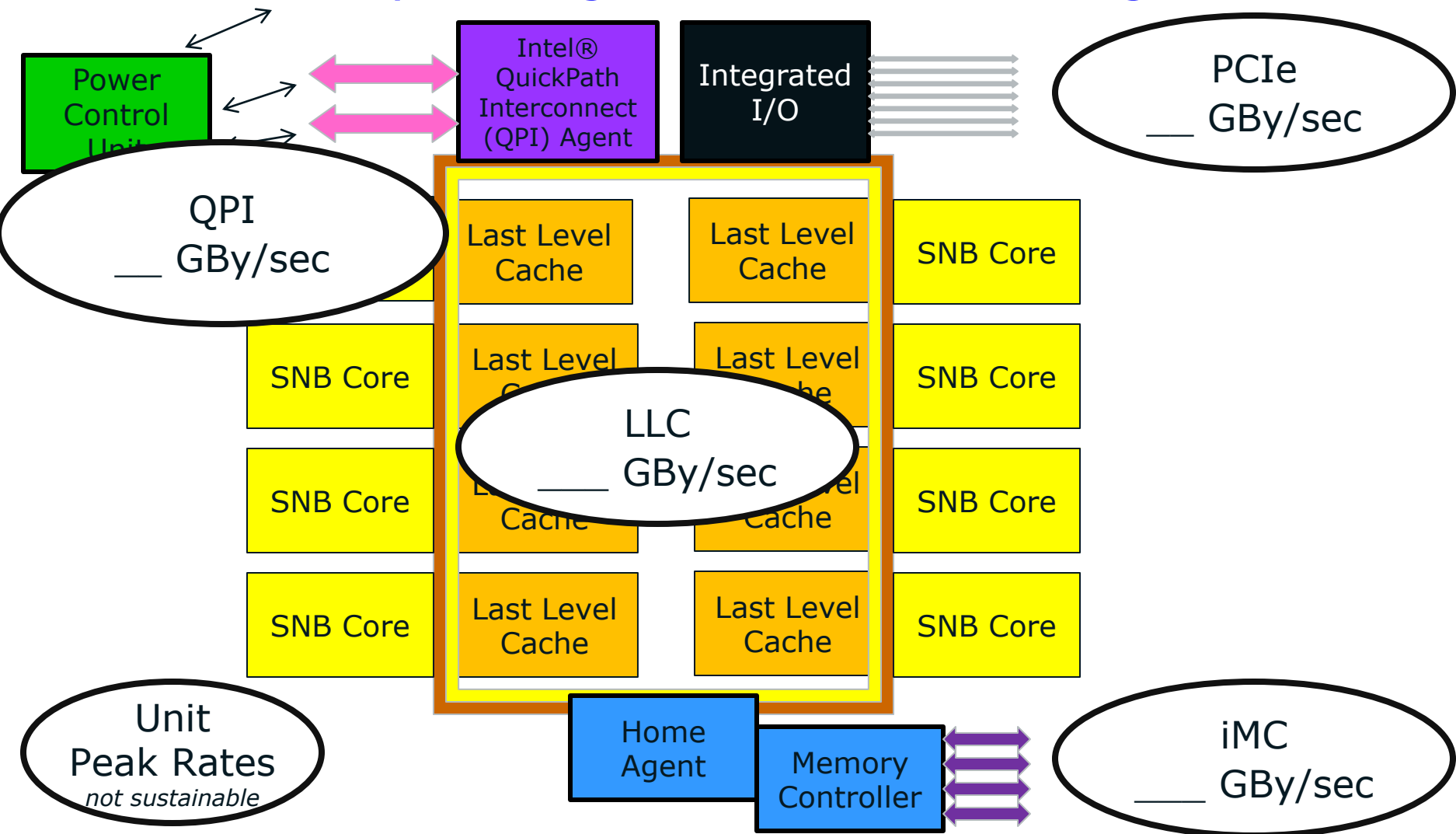
## Foundations of SNB-EP Performance

# Put Eight Cores on a High BW Interconnect: The Ring



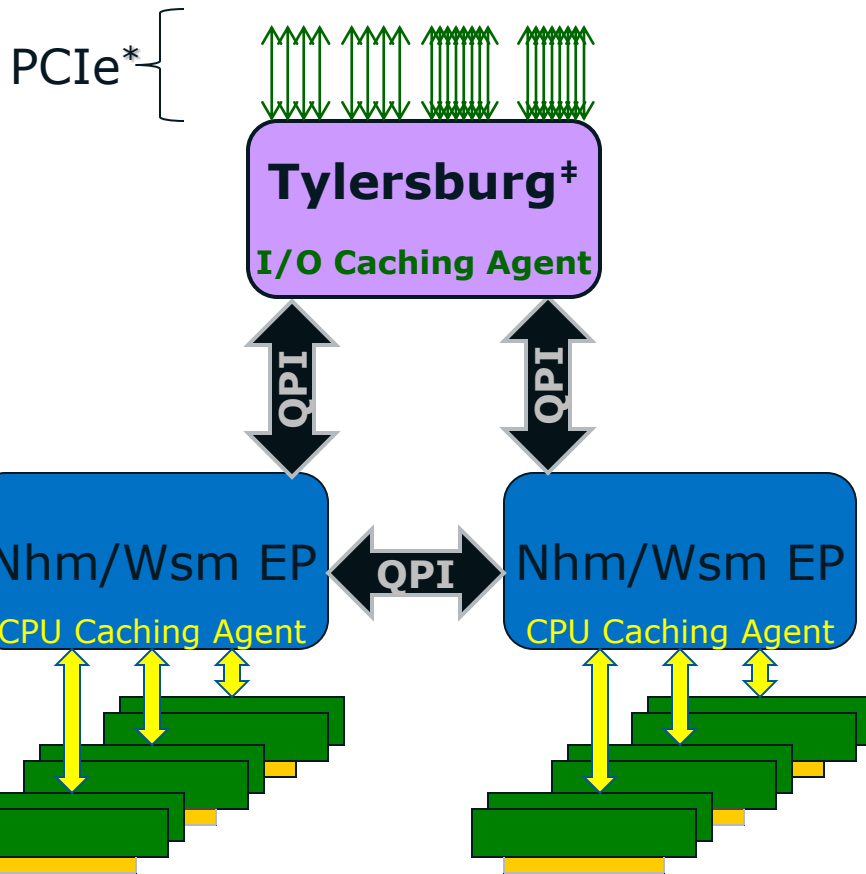
# Foundations of SNB-EP Performance

## Add an LLC, System Agents, and Power Management

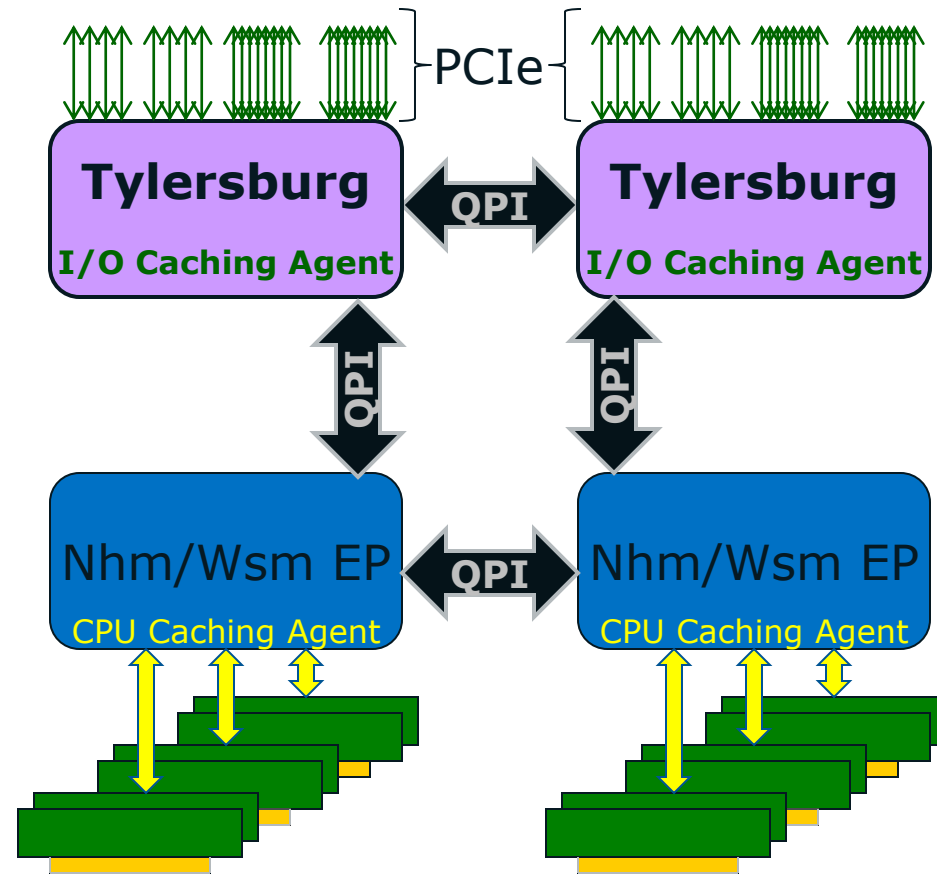


# Thurley Platform Review

## Single IOH



## Dual IOH



‡Note: PCH omitted in diagrams

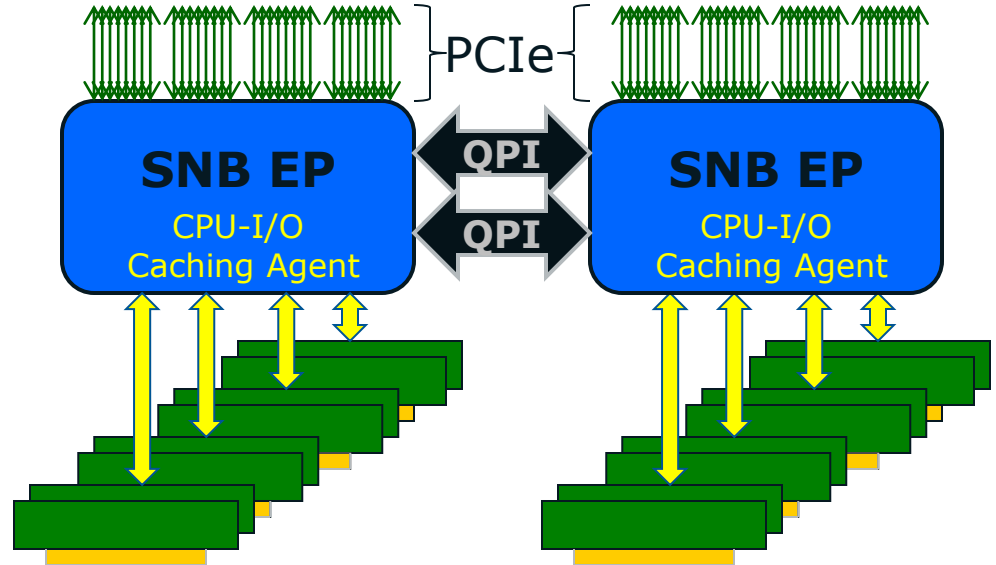
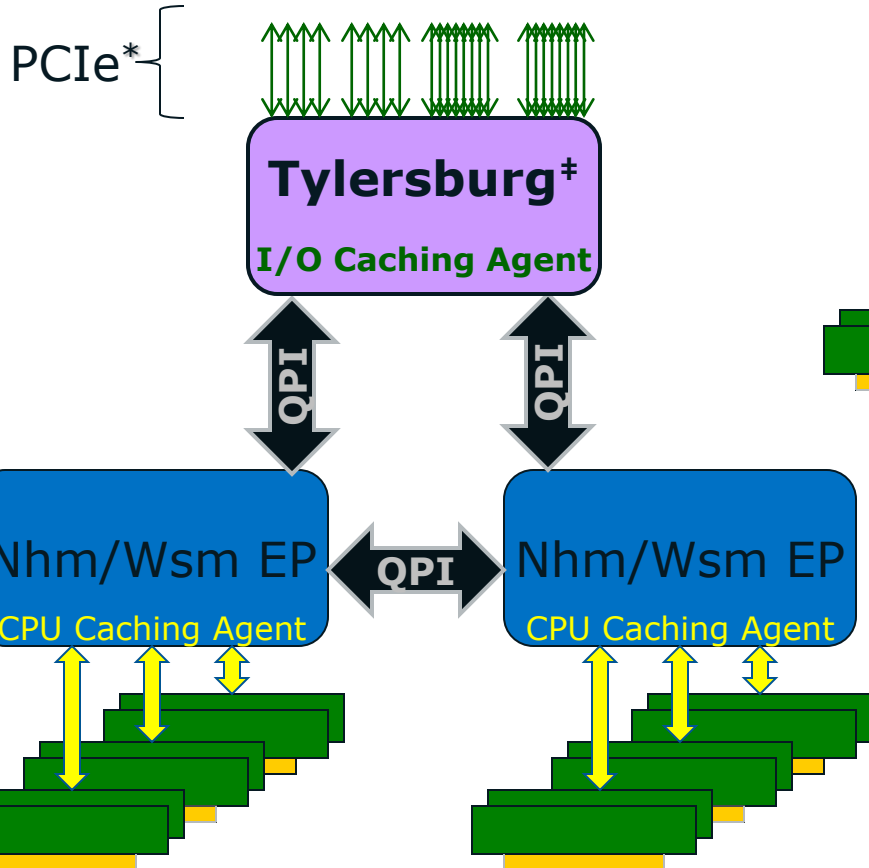


# Foundations of SNB-EP Performance

## Higher Performance Platform

Romley

Thurley



**Topology Performance Changes**

- 40 Lanes of 8 GT/s Integrated PCIe
- Dual Inter-processor QPI links
- Four higher speed memory channels

‡Note: PCH omitted in diagrams

## Foundations of SNB-EP Performance

### Focus on I/O Performance

#### □ **PCIe G3: 8 GT/s vs. 4 GT/s**

- DMI2 (4 GT/s) vs. DMI1 (2 GT/s) (not shown in diagram)

#### □ **I/O capacity scales with sockets (memory BW)**

#### □ **Inherent benefit from Integration:**

QPI link to I/O controller replaced with direct ring interconnect reducing latency and increasing BW

#### □ **CPUs and PCIe are a unified Caching Agent**

- Less resource partitioning
  - More scalable, higher performance
- Reduces the latency of cacheable traffic
- PCIe acts under the auspices of and uses the LLC (more later)

## Foundations of SNB-EP Performance

### Focus on I/O Performance (cont'd)

#### □ **I/O-related Optimizations**

- Double width data buses in the I/O unit
- ReadCurrent semantics rather the Code Read
  - Potentially reduces memory write traffic – maybe a lot
- Inbound writes
  - Cache line pre-allocated but ownership can be preempted
  - Prefetch of data (for write merging)

#### □ **40 lanes vs. 36 lanes**

#### □ **Physical address range (46b vs. 41b)**

## Foundations of SNB-EP Performance

### Focus on I/O Performance (cont'd)

- **Intel® Direct Data I/O Technology (Intel® DDIO): IIO allocates and transfers directly into LLC**
  - IIO cache allocating is generally limited to 2 (of 20) ways
    - Can use a line that's already been allocated by, say, a core
  - Circular buffers of reasonable size (a few to ten MBy) can reside in the LLC *and, in practice, almost never be written.*
  - Making use of this can effectively double the achievable I/O bandwidth of a core and of a socket.
  - Permits practically linear scaling as multiple high bandwidth I/O devices are added (e.g., 10 GbE adapters) with achieving nearly zero read and write bandwidth to memory
    - Saves power, too

## Mid-Game Summary

### □ **Improved performance by improving the parts**

- Sandy Bridge core
- On-die interconnect (“Ring”)
- More and faster memory channels with improved scheduling
- Faster inter-socket communication (Intel® QPI)
- Integrating and accelerating I/O

### □ **Coming Up in the Next Half:**

## **Performance with Power Efficiency**

A graphic consisting of several overlapping blue rectangular shapes of varying shades and positions, creating a layered effect. The text "Energy Efficient Load Line" is centered within the largest, lightest blue shape.

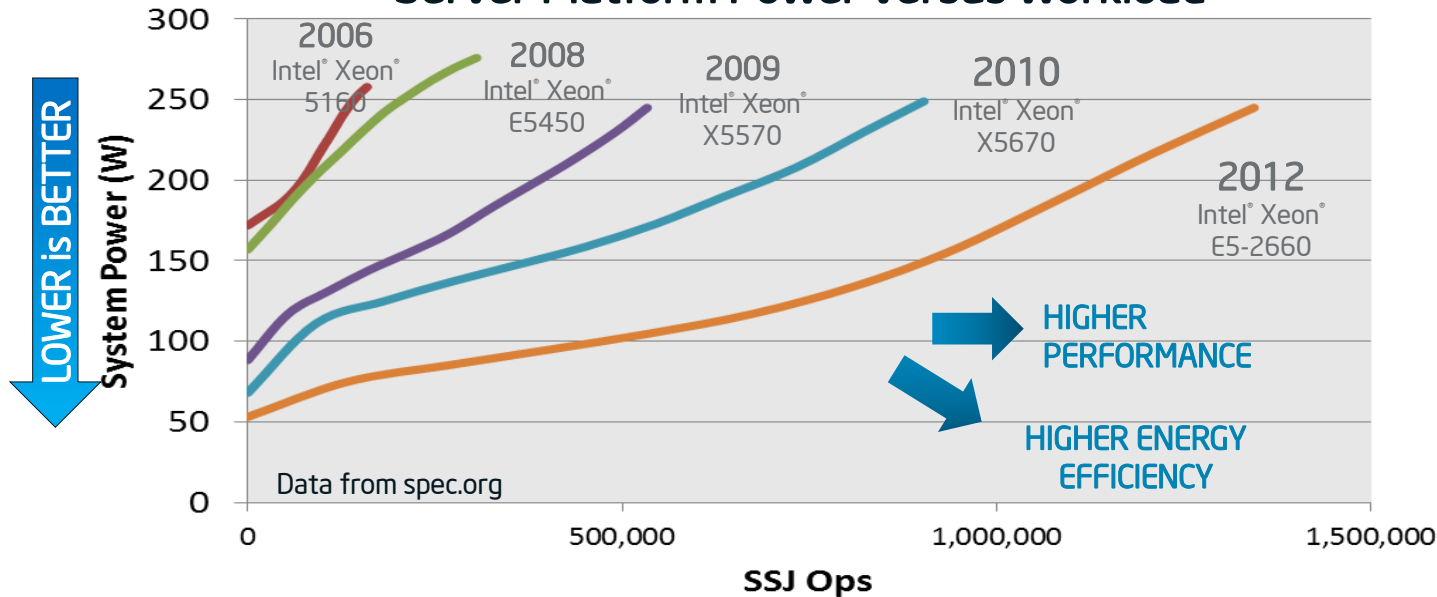
# Energy Efficient Load Line

# Energy Efficient Load Line

Performance:  
45% CAGR

Energy  
Efficiency:  
60% CAGR

## Server Platform Power versus Workload



- **Platform efficiency at low Power**
  - CPU and DRAM VR Phase shedding
- **Scalable Uncore Power**
  - Uncore voltage frequency scaling
- **Scalable Memory Power**
  - Multi-rank slow CKE

- **Processor Power**
  - Energy Perf BIAS, Dynamic Switching
- **I/O Power management**
  - QPI L0p/L1, PCIE ASPM L1

## Significant Improvement to Proportional Energy

# Dynamic Performance Load Line

## PCU dynamically adjusts to OS Power Management Policy

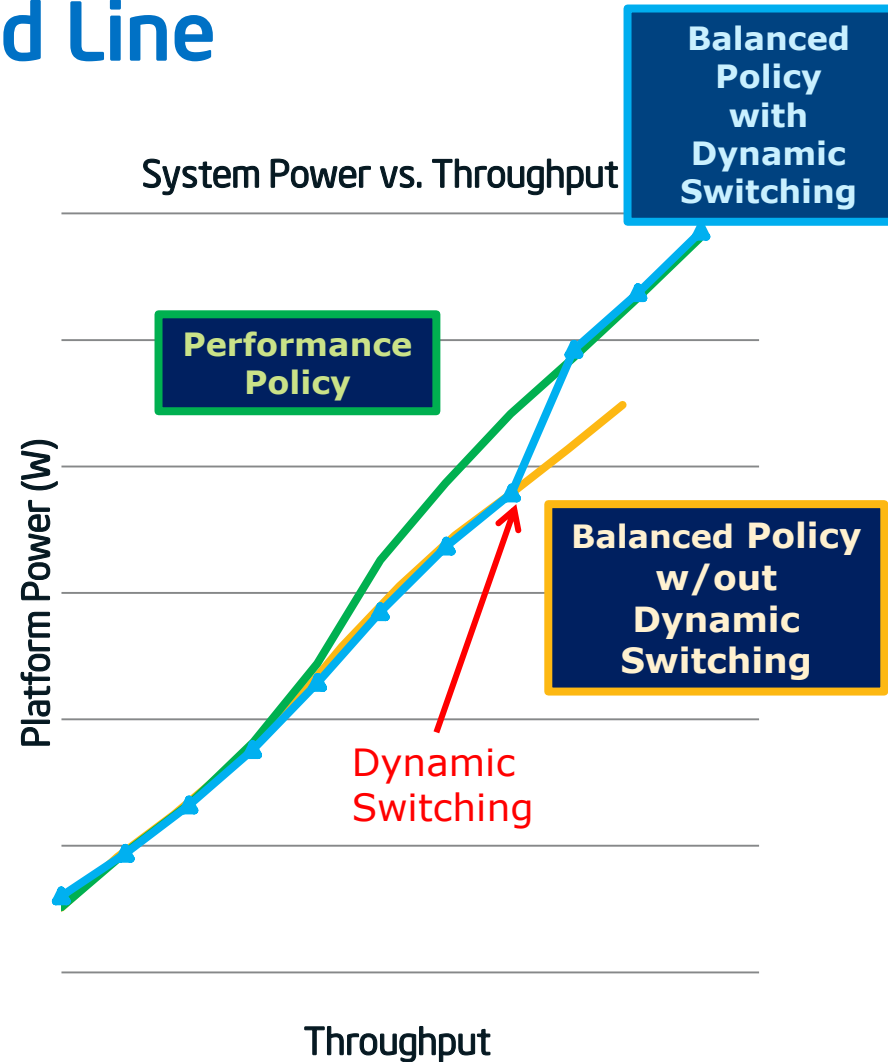
- OS communicates Policy through EPB (Energy Perf BIAS)
- PCU monitors and adjusts autonomously on die power saving engines

## PCU automatically adjusts for Performance at high utilization

- Leverages EPB to switch into performance mode when necessary

## Optimized across a range of workloads

- Single-threaded workloads
- Multi-threaded workloads



**PCU works synergistically with OS Power Policy**



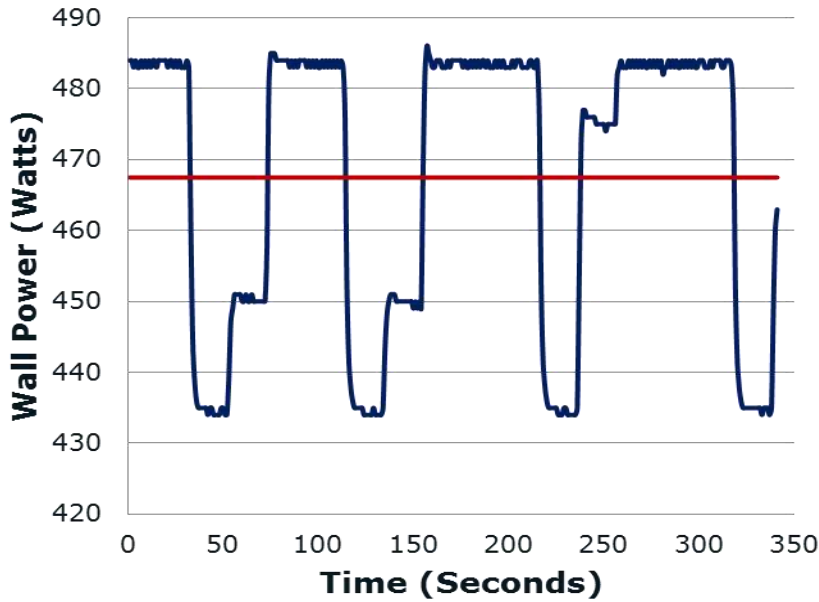


# Energy Efficiency in the Data Center



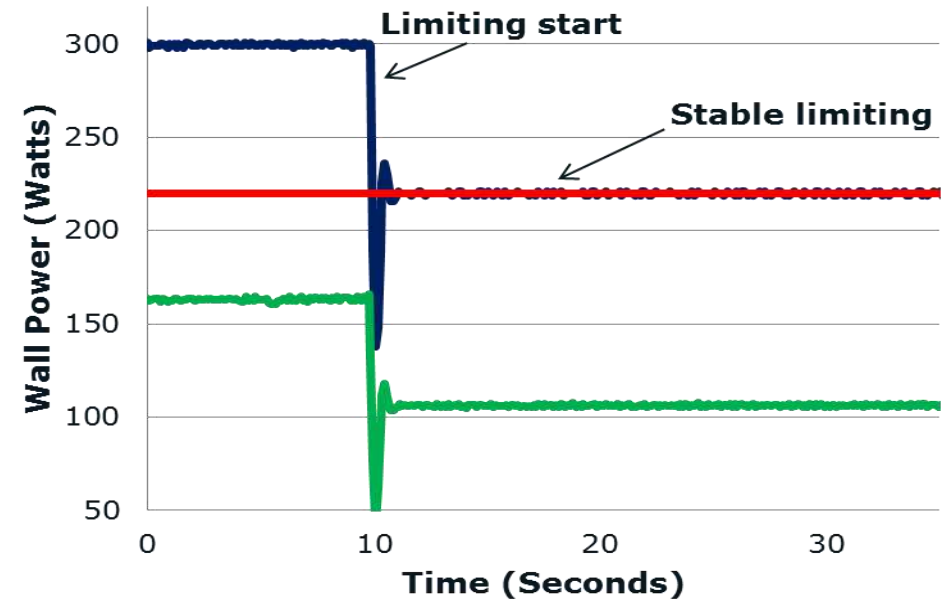
# Running Average Power Limiting (RAPL)

**Power Limiting Quality:  
Based on P state Control**



— Wall Power      — Power Limit

**Power Limiting Quality:  
Based on RAPL**

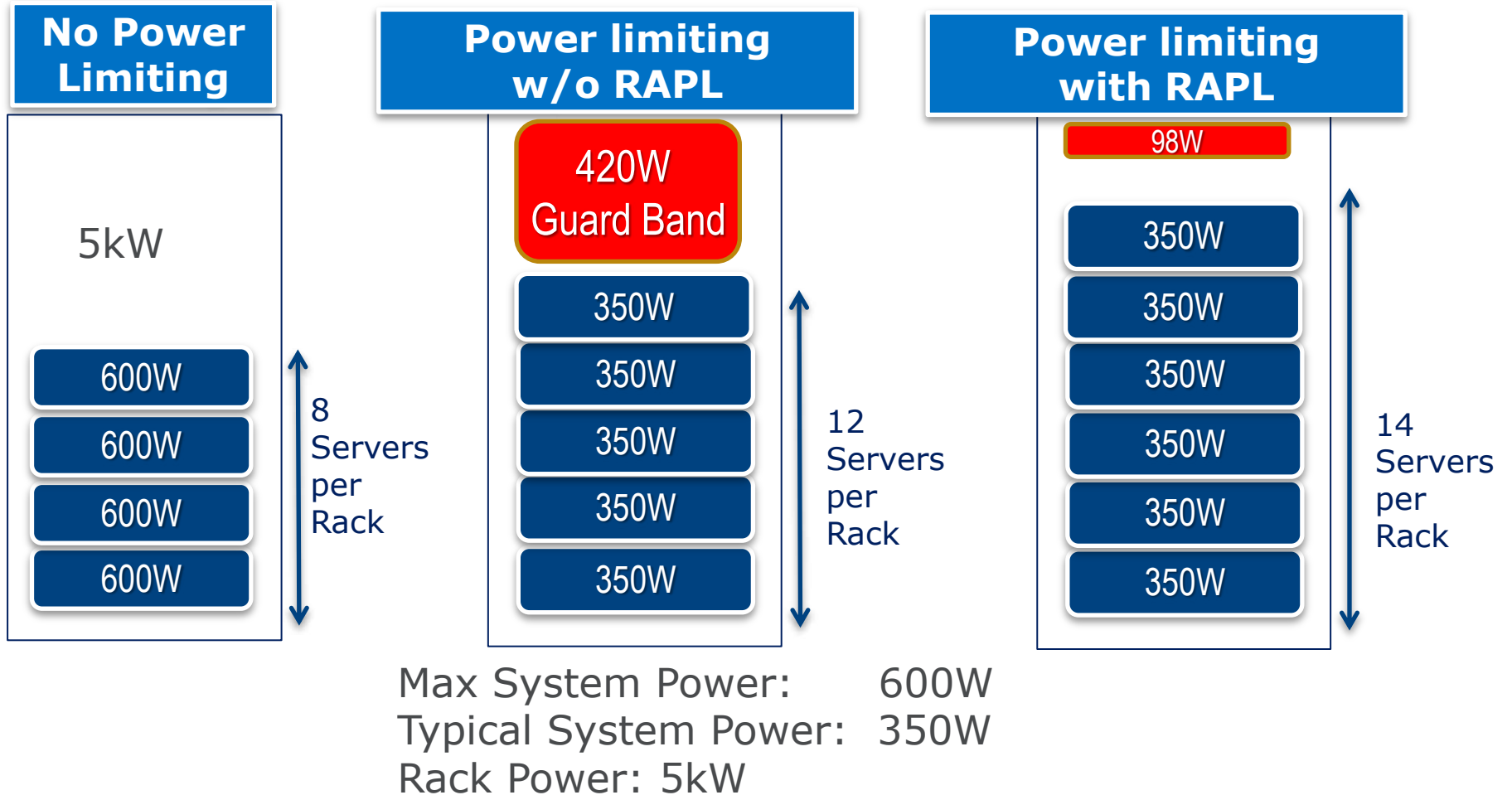


— PSU readings    — CPU readings    — Power limit

**RAPL gives accurate and stable power limiting than P state control**

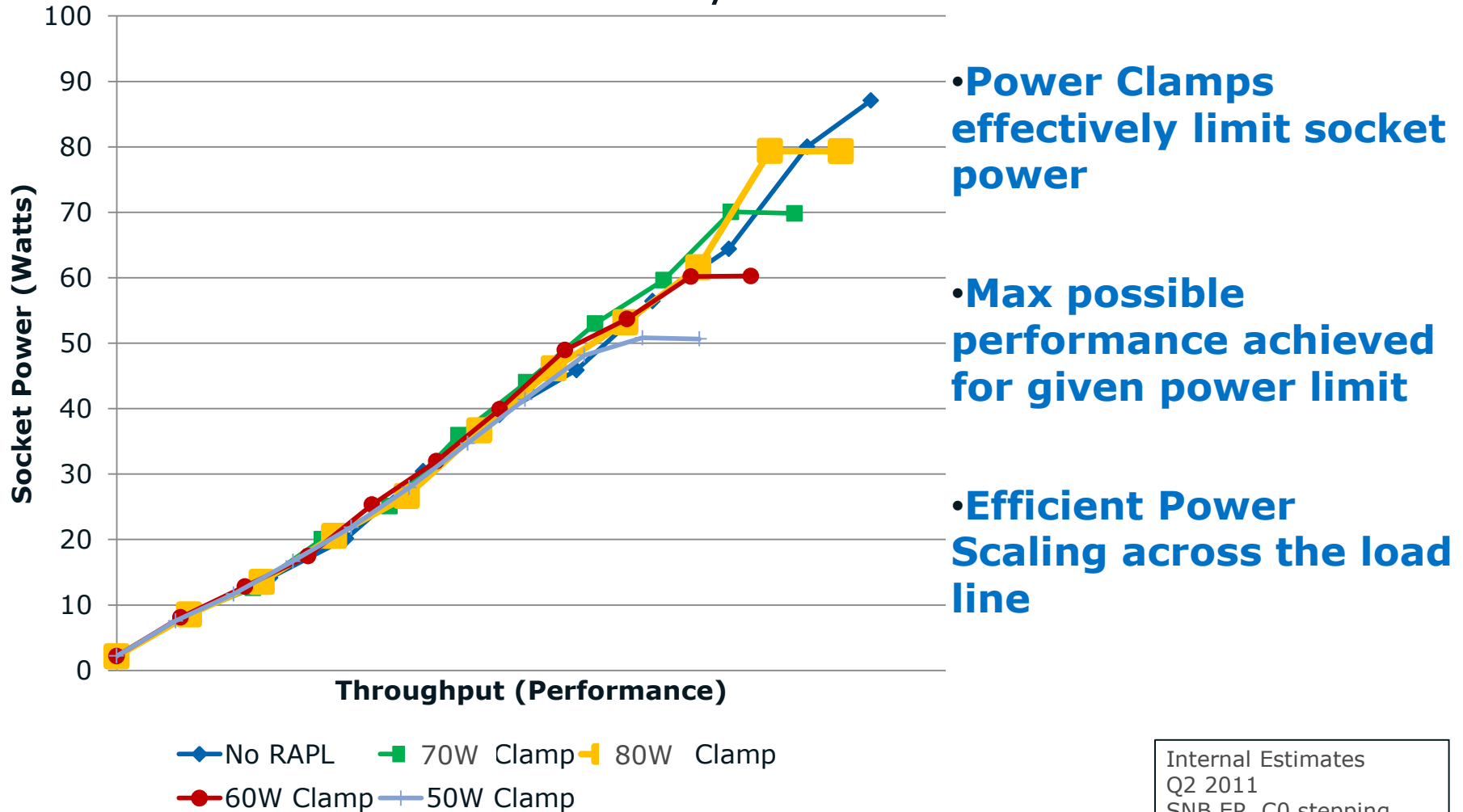
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# Improved Efficiency with RAPL



Improved Power Limiting Accuracy Allows for Smaller Guard bands and Increased Rack Density.

# Socket RAPL & the Power/Performance Load Line



Internal Estimates  
 Q2 2011  
 SNB EP, C0 stepping

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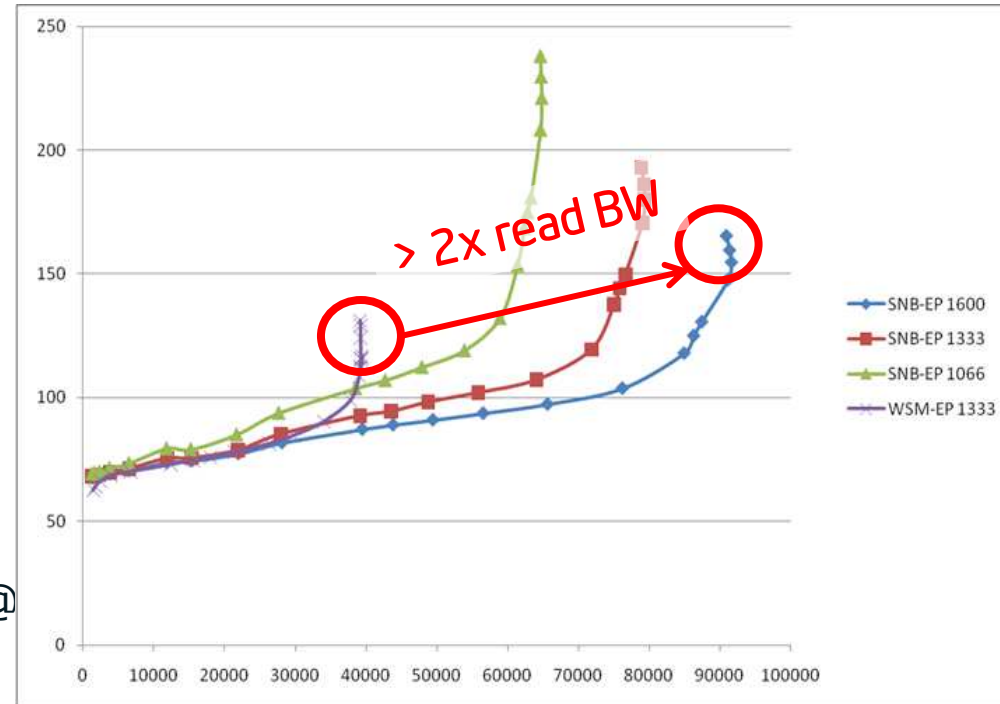


# Maximum Performance



## Memory Latency Optimizations

- Early Snoop
- Dynamic Direct 2 Core
- Uncore Frequency Change
- Dynamic Memory CKE Disable
- New LLC Prefetcher
- **Distributed L3**
  - Theoretical Peak: ~844GB/s (1s @ 3.3GHz w/ 8 cores)
  - Core->L3 Read Throughput: >250GB/s (1s @ 3.3GHz w/ 8 cores)
- **Dual Load Ports on L1 D-Cache**
- **SandyBridge Turbo 2.0**



**>2x max bandwidth from Xeon 5600 on read BW**

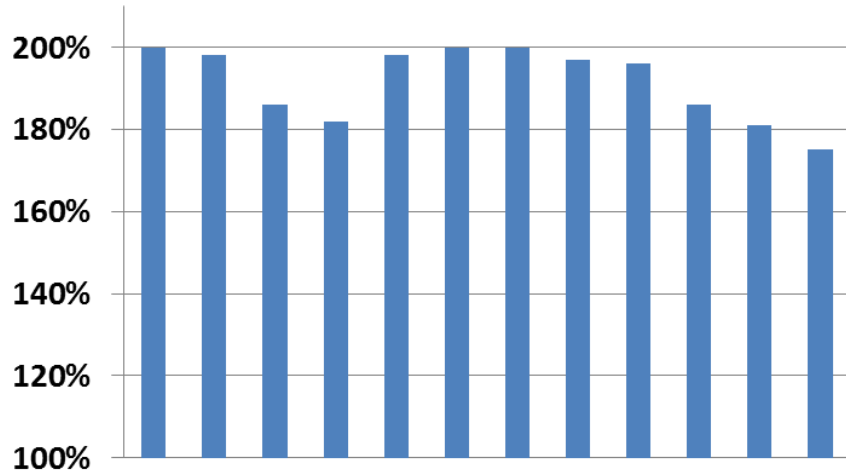
- 3->4 channels (+33%)
- 1333->1600 (+20%)
- Improved Efficiency (+~40%)

### Benchmark Notes:

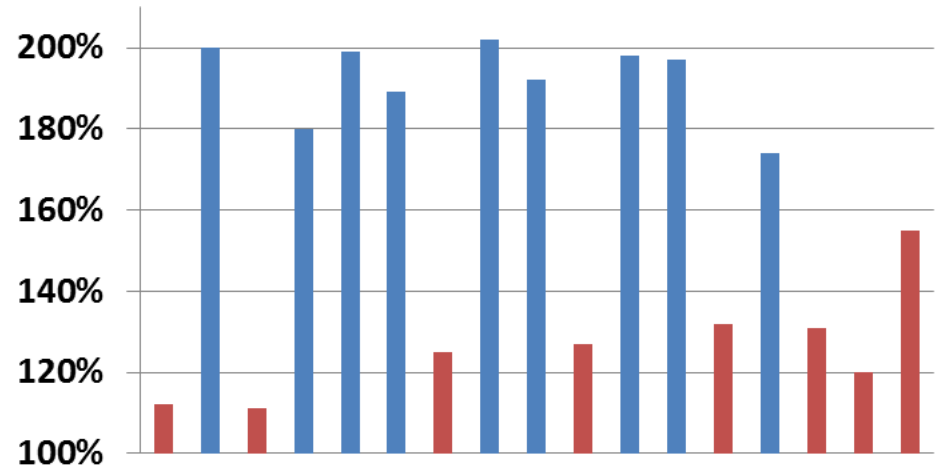
- Intel internal tool for BW and Latency

# Comparison of 4 core to 8 core Scaling @ 3.3GHz

**Integer Throughput Workloads**



**Floating Point Throughput Workloads**



- Core sensitive apps in both INT and FP show excellent performance scaling
- Memory sensitive apps show less scaling (as expected shown in red)

**Internal Testing – Estimate**

4c: SNB E5-2643 w/out Turbo (1 DPC, DDR 1600)  
 8c: SNB E5-2690 w/ Turbo (2 DPC, DDR 1600)  
 ICC 12.1 / RHEL 6.1 / 2.6.32.131

Apps highlighted in Red are Memory Bandwidth sensitive

**Intel® Xeon® E5 uncore provides significant core Scaling**

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# Configuration Details for Foil #25

For the SPEC benchmarks, please see <http://www.spec.org> for more information

**Configuration Details:** As of 31 May 2012

## **SAP\* SD 2-tier**

2x Intel Xeon processor X5690 (12M cache, 3.46GHz, 6.40GT/s Intel QPI) score 5220 SD users. Certification #2011005. Source: [http://download.sap.com/download.epd?context=40E2D9D5E00EEF7C4B299992CE278ECED5166ED278FF20DF78759DC5B1E5FE79](http://download.sap.com/download.epd?context=40E2D9D5E00EEF7C4B299992CE278ECED5166ED278FF20DF78759DC5B1E5FE79;);  
2x Intel Xeon processor E5-2690 (20M cache, 2.9GHz, 8.0GT/s Intel QPI) score 7865 SD users. Source: <http://download.sap.com/download.epd?context=40E2D9D5E00EEF7C5DDDB3927818D671E00ECF023B5CE29EE68B565E9F19F1254>

## **SPECvirt\_sc\*2011**

2x Intel® Xeon® processor X5690 (6C, 12M, 3.06GHz) score 1367 @ 84 VMs. Source: [http://www.spec.org/virt\\_sc2010/results/res2011q1/virt\\_sc2010-20110209-00022-perf.html](http://www.spec.org/virt_sc2010/results/res2011q1/virt_sc2010-20110209-00022-perf.html);  
2x Intel® Xeon® processor E5-2690 (8C, 2.9GHz, C0) score 2,388 @ 150 VMs. Source: [http://www.spec.org/virt\\_sc2010/results/res2012q2/virt\\_sc2010-20120403-00045-perf.html](http://www.spec.org/virt_sc2010/results/res2012q2/virt_sc2010-20120403-00045-perf.html)

## **SPECpower\_ssj\*2008**

metrics for SPECpower are efficiency based and expressed as ssj\_ops/watt.

2x Intel Xeon processor X5675 (12M cache, 3.45GHz, 6.40GT/s Intel QPI) score 3,329. Source: [http://www.spec.org/power\\_ssj2008/results/res2011q4/power\\_ssj2008-20110713-00386.html](http://www.spec.org/power_ssj2008/results/res2011q4/power_ssj2008-20110713-00386.html);  
2x Intel Xeon processor E5-2660 (20M cache, 2.2GHz, 8.0GT/s Intel QPI, C1) score 5,088. Source: [http://www.spec.org/power\\_ssj2008/results/res2012q2/power\\_ssj2008-20120427-00454.html](http://www.spec.org/power_ssj2008/results/res2012q2/power_ssj2008-20120427-00454.html)

## **TPC-E\***

2x Intel Xeon processor X5690 (12M Cache, 3.46GHz, 2P/12C/24T) referenced as published at 1,284.14 tpsE, \$250 USD/tpsE, available 5/4/11. Source: [http://www.tpc.org/tpce/results/tpce\\_result\\_detail.asp?id=111050403](http://www.tpc.org/tpce/results/tpce_result_detail.asp?id=111050403);  
Intel: 2x Intel Xeon processor E5-2690 (20M cache, 2.9GHz, 2P/16C/32T) referenced as published at 1,863.23 tpsE, \$207.85 USD/tpsE, available 3/6/12. Source: [http://www.tpc.org/tpce/results/tpce\\_result\\_detail.asp?id=112030601](http://www.tpc.org/tpce/results/tpce_result_detail.asp?id=112030601)

## **VMmark\* 2**

2x Intel Xeon processor X5690 (12M cache, 3.46GHz, 6.40GT/s Intel QPI) score 7.59 @ 7 Tiles. Source: <http://www.vmware.com/a/assets/vmmark/pdf/2011-10-18-Fujitsu-RX300S6.pdf>;  
2x Intel Xeon processor E5-2690 (20M cache, 2.9GHz, 8.0GT/s Intel QPI, C1) score 11.13 @ 10 Tiles. Source: <http://www.vmware.com/a/assets/vmmark/pdf/2012-05-15-HP-DL360pG8.pdf>

## **TPC-C\***

2x Intel Xeon processor X5690 (12M Cache, 3.46GHz, 2P/12C/24T) referenced as published at 1,053,100 tpmC, \$0.57 USD/tpmC, available 6/20/11. Source: [http://www.tpc.org/tpcc/results/tpcc\\_result\\_detail.asp?id=111120802](http://www.tpc.org/tpcc/results/tpcc_result_detail.asp?id=111120802);  
2x Intel Xeon processor E5-2690 (20M cache, 2.9GHz, 8.0GT/s Intel QPI) referenced as published at 1,503,544 tpmC, \$0.53 USD/tpmC, available 4/11/12. Source: [http://www.tpc.org/tpcc/results/tpcc\\_result\\_detail.asp?id=112041101](http://www.tpc.org/tpcc/results/tpcc_result_detail.asp?id=112041101)

## **SPECjbb\*2005**

2x Intel Xeon processor X5690 (12M cache, 3.46GHz, 6.40GT/s Intel QPI) score 975,257 bops, 487,629 bops/JVM. Source: <http://www.spec.org/osg/jbb2005/results/res2011q1/jbb2005-20110215-00950.html>;  
2x Intel Xeon processor E5-2690 (2.9GHz, 8C) score 1,584,567 bops. Source: <http://www.spec.org/osg/jbb2005/results/res2012q1/jbb2005-20120306-01056.html>

## **SPECint\*\_rate\_base2006**

2x Intel Xeon processor X5690 (12M cache, 3.45GHz, 6.40GT/s Intel QPI) baseline score 425. Source: <http://www.spec.org/cpu2006/results/res2012q2/cpu2006-20120322-20154.html>  
2x Intel Xeon processor E5-2690 (20M cache, 2.9GHz, 8.0GT/s Intel QPI) baseline score 671. Source: <http://www.spec.org/cpu2006/results/res2012q1/cpu2006-20120307-19618.html>

## **SPECjEnterprise\*2010**

2x Intel Xeon processor X5690 (12M cache, 3.46GHz, 6.40GT/s Intel QPI) score 5,427 EjOPS. Source: <http://www.spec.org/jEnterprise2010/results/jEnterprise2010.html>;  
2x Intel Xeon processor E5-2690 (20M cache, 2.9GHz, 8.0GT/s Intel QPI) score 8,310.19 EjOPS. Source: <http://www.spec.org/jEnterprise2010/results/jEnterprise2010.html>

## **SPECfp\*\_rate\_base2006**

2x Intel Xeon processor X5690 (12M cache, 3.45GHz, 6.40GT/s Intel QPI) baseline score 271. Source: <http://www.spec.org/cpu2006/results/res2012q1/cpu2006-20111219-19195.html>  
2x Intel Xeon processor E5-2690 (20M cache, 2.9GHz, 8.0GT/s Intel QPI) baseline score 496. Source: <http://www.spec.org/cpu2006/results/res2012q1/cpu2006-20120307-19617.html>

## **STREAM\*\_MP Triad (NTW)**

2x Intel Xeon processor X5690 (12M cache, 3.45GHz, 6.40GT/s Intel QPI) TRIAD score 42GB/s. Source: Intel TR#1241  
2x Intel Xeon processor E5-2690 (20M cache, 2.9GHz, 8.0GT/s Intel QPI, C1) score 79.5 GB/s. Source: Intel TR#1241

## **Linpack**

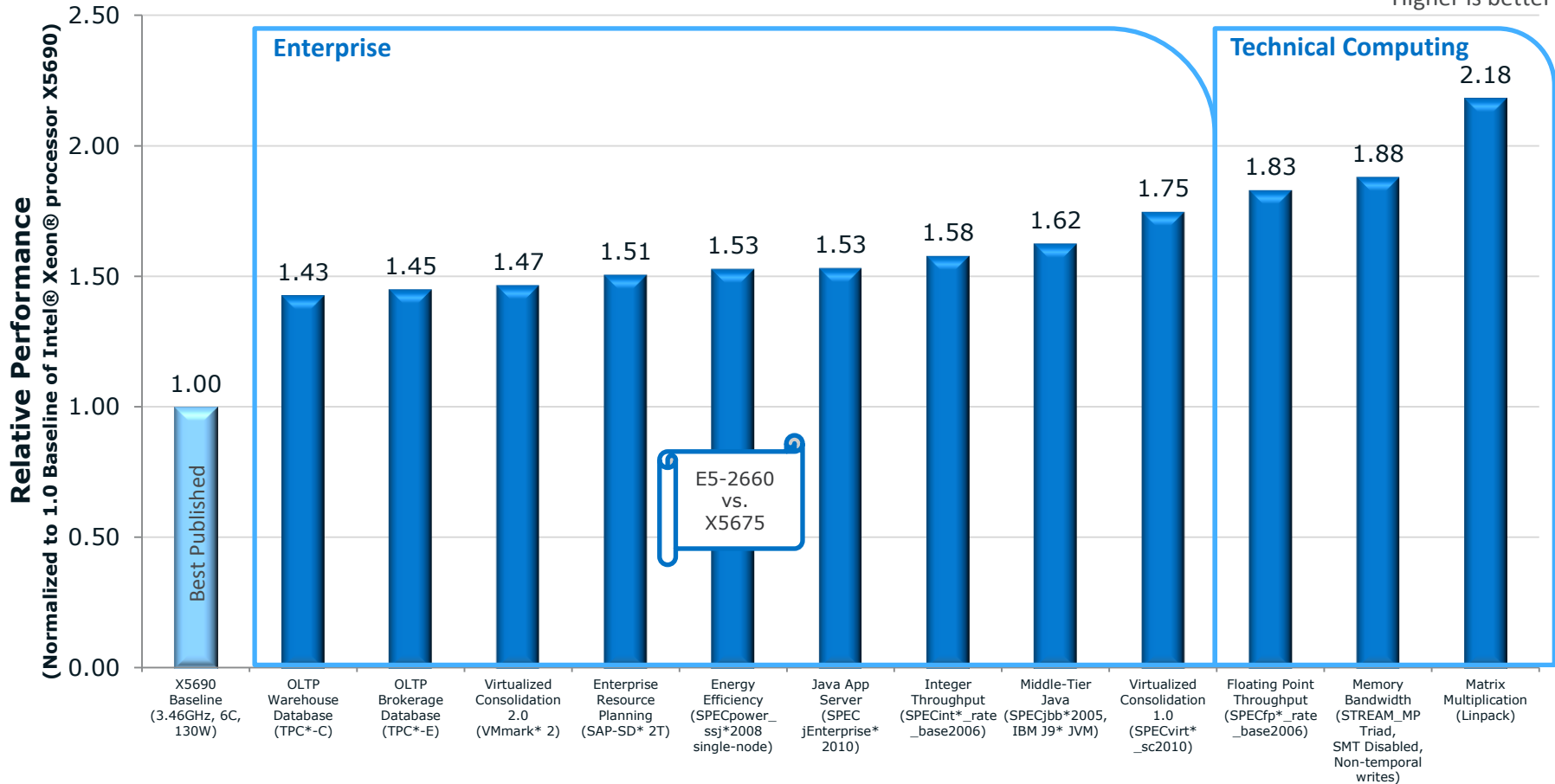
2x Intel Xeon X5690 (12M cache, 3.45GHz, 6.40GT/s Intel QPI) score 159.4. Source: Intel TR#1236  
2x Intel Xeon processor E5-2690 (20M cache, 2.9GHz, 8.0GT/s Intel QPI, C1) score 347.7. Source: Intel TR#1236  
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# Intel® Xeon® Processor E5-2600 Product Family Generational Performance Summary

Intel® Xeon® Processor E5-2690 (8C, 2.9GHz, 135W) vs. Intel® Xeon® Processor X5690 (6C, 3.46GHz, 130W)

Turbo Enabled  
Higher is better



**Intel® Xeon® processor E5-2690 delivers performance gains up to 2X**

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Linpack performance may vary based on thermal solution.  
Configuration Details: Please reference foil 24 for details.

For more information go to <http://www.intel.com/performance>

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